



## Materials Declaration Form

<b>IPC Form Type *</b>	1752 Distribute	<b>Version</b>	2
<b>Sectionals *</b>	Material Info Manufacturing Info	<b>Subsectionals *</b>	A-D  <i>* : Required Field</i>

Supplier Information			
<b>Company Name *</b>	STMicroelectronics	<b>Response Date *</b>	2017-08-08
<b>Contact Name *</b>	Refer to Supplier Comment section		Refer to Supplier Comment section
<b>Authorized Representative *</b>	Giuseppe Vitali Palma	<b>Representative Title</b>	ADG MD Champion
<b>Representative Phone *</b>	Refer to Supplier Comment section	<b>Representative Email *</b>	Refer to Supplier Comment section
<b>Supplier Comment</b>	Online Technical Support - STMicroelectronics : <a href="http://www.st.com/web/en/support/support.html">http://www.st.com/web/en/support/support.html</a>		

**Uncertainty Statement**

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**Legal Statement**

<b>Supplier Acceptance *</b>	true	<b>Legal Declaration *</b>	Standard
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**Legal Statement**

Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as omprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
STF43N60DM2	XSPF*FQ6LB62	A	3068	2017-08-08
Amount	UoM	Unit type	ST ECOPACK Grade	
1900.00	mg	Each	ECOPACK2	

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles		 life.augmented
NA	NA	NA		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
NA	Tin (Sn), matte	Copper Alloy		

Package Designator	Size	Nbr of instances	Shape	
SIP	10.2-16.15-4.5	3	Through-hole	
Comment	TO 220 ISO FULL PACK IN LINE			

QueryList : RoHS Directive 2011/65/EU-July 2011 – Annex II amended by Directive 2015/863-April 2015	
Query	Response
1 - Product(s) meets EU RoHS requirement without any exemptions	FALSE
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	FALSE
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	TRUE
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions	FALSE
Exemption Id.	Description
7a	Lead in high melting temperature type solders (i.e. lead- based alloys containing 85 % by weight or more lead)

Query : California Prop65 list, dated 27th January 2017			
Query			Response
1 - The product does not contain identified substance from California Prop 65 List, no exposure to consumers is foreseen			FALSE
2 - The product is containing below substance(s) from California Prop 65 List, no exposure to consumers is foreseen			TRUE
Substance	amount in product (mg)	Application	ppm in product
Nickel	0.83	Die back side metal - Leadframe metal	436
Lead	19.68	Soft solder	10358

QueryList : REACH-12th January 2017				
Query				Response
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				true
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

Material Composition Declaration : note : Substance present with less 0.001mg will not be declared in this document						Mfr Item Name	XSPF*FQ6LB2									
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)				
Die or Dies (choose)	Other inorganic materials	23.466	mg	supplier	die	Silicon (Si)	7440-21-3		22.535	mg	960326	11861				
				supplier	metallization	Aluminium (Al)	7429-90-5		0.448	mg	19091	236				
				supplier	Passivation	Silicon Nitride	12033-89-5		0.106	mg	4517	56				
				supplier	Passivation	Silicon Oxide	7631-86-9		0.158	mg	6733	83				
				supplier	back side metallization	Titanium (Ti)	7440-32-6		0.011	mg	469	6				
				supplier	back side metallization	Nickel (Ni)	7440-02-0		0.154	mg	6563	81				
				supplier	back side metallization	Silver (Ag)	7440-22-4		0.054	mg	2301	28				
				supplier	alloy	Copper (Cu)	7440-50-8		604.469	mg	997498	318142				
				supplier	alloy	Iron (Fe)	7439-89-6		0.605	mg	998	318				
				supplier	alloy	Iron Phosphide (FeP)	26508-33-8		0.182	mg	300	96				
Leadframe	Copper & its alloys	605.985	mg	supplier	metallization	Nickel (Ni)	7440-02-0		0.674	mg	1113	355				
				supplier	metallization	Phosphorus (P)	12185-10-3		0.055	mg	91	29				
				supplier	solder	Lead (Pb)	7439-92-1	7a-Lead in high me	19.681	mg	955017	10358				
				supplier	solder	Silver (Ag)	7440-22-4		0.515	mg	24991	272				
				supplier	solder	Tin (Sn)	7440-31-5		0.412	mg	19992	217				
				Soft solder	Solder	20.608	mg	JIG - R	solder	Aluminium (Al)	7429-90-5		1.080	mg	996310	568
								supplier	wire	Magnesium (Mg)	7439-95-4		0.004	mg	3690	2
								supplier	mold compound	Quartz	14808-60-7		870.094	mg	700000	457944
								supplier	mold compound	Silica, vitreous	60676-86-0		93.224	mg	75000	49065
								supplier	mold compound	Epoxy resin	25068-38-6		174.019	mg	140000	91589
supplier	mold compound	phenol resin	29690-82-2						87.009	mg	70000	45794				
Bonding wires	Other inorganic materials	1.084	mg	supplier	mold compound	metal hydroxide	Proprietary		12.430	mg	10000	6542				
				supplier	mold compound	carbon black	1333-86-4		6.215	mg	5000	3271				
				Connections coating	Solder	5.866	mg	supplier	solder alloy	Tin (Sn)	7440-31-5		5.866	mg	1000000	3087